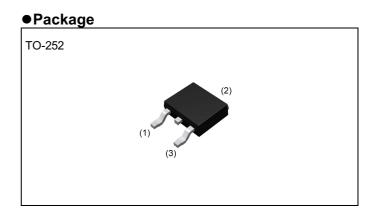


| V _{DSS} | 800V |
|----------------------------|-------|
| R _{DS(on)} (Max.) | 0.90Ω |
| Ι _D | ±6A |
| P _D | 83W |



Inner circuit

(2) (1) Gate (2) Drain (1) 0 (1) 0 (1) 0 (1) 0 (1) 0 (1) 0 (1) 0 (1) 0 (1) 0 (1) 0 (1) 0 (1) 0 (2) 0 (2) 0 (2) 0 (2) 0 (2) 0 (3) 0 (3) 0 (3) 0 (3) 0 (4) 0 (5)

Application

Features

1) Low on-resistance

3) Parallel use is easy

4) Pb-free plating ; RoHS compliant

2) Fast switching

Switching applications

Marking specification

| Marking | R8006KND3 |
|---------|-----------|
|---------|-----------|

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

| Parameter | Symbol | Value | Unit | |
|---|------------------|--------------------|------|----|
| Drain - Source voltage | | V _{DSS} | 800 | V |
| Continuous drain current | | ۱ _D *1 | ±6 | А |
| Pulsed drain current | | I_{DP}^{*2} | ±18 | А |
| Coto Courros voltario | Static | | ±20 | V |
| Gate - Source voltage | AC (f>1Hz) | V_{GSS} | ±30 | V |
| Avalanche current, single pulse | | I _{AS} | 1.2 | А |
| Avalanche energy, single pulse | | E _{AS} *3 | 76 | mJ |
| Power dissipation $(T_c = 25^{\circ}C)$ | P _D | 83 | W | |
| Junction temperature | Tj | 150 | °C | |
| Operating junction and storage te | T _{stg} | -55 to +150 | °C | |

•Thermal characteristics

| Deremeter | Cumph of | Values | | | 1.1.5.16 |
|--|----------------------|--------|------|------|----------|
| Parameter | Symbol | Min. | Тур. | Max. | Unit |
| Thermal resistance, junction - case | $R_{th(j-c)}^{*4}$ | - | - | 1.5 | °C/W |
| Thermal resistance, junction - ambient | R _{th(j-a)} | - | - | 147 | °C/W |
| Soldering temperature, wavesoldering for 10s | T _{sold} | - | - | 265 | °C |

• Static characteristics ($T_a = 25^{\circ}C$)

| Deremeter | Symbol Conditions - | | Values | | | Unit |
|--|------------------------|--|--------|------|------|------|
| Parameter | | | Min. | Тур. | Max. | Unit |
| Drain - Source breakdown voltage V _(BR) | | V _{GS} = 0V, I _D = 1mA | 800 | - | - | V |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 800V, V _{GS} = 0V | - | - | 100 | μA |
| Gate - Source leakage current | I _{GSS} | V_{GS} = ±20V, V_{DS} = 0V | - | - | ±100 | nA |
| Gate threshold voltage | V _{GS(th)} | $V_{DS} = V_{GS}$, $I_D = 4mA$ | 2.5 | 3.5 | 4.5 | V |
| Static drain - source on - state resistance | R _{DS(on)} *5 | V _{GS} = 10V, I _D = 3A | - | 0.75 | 0.90 | Ω |



•Dynamic characteristics (T_a = 25°C)

| Deremeter | Currence of | Conditions | Values | | | L locit | |
|---|-----------------------|---------------------------------------|--------|------|------|---------|--|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit | |
| Gate resistance | R _G | f = 1MHz, open drain | - | 3 | - | Ω | |
| Input capacitance | C _{iss} | V _{GS} = 0V, VDS = 100V | - | 650 | - | | |
| Output capacitance | C _{oss} | f = 1MHz | - | 45 | - | | |
| Effective output capacitance energy related | C _{o(er)} *6 | V _{GS} = 0V | - | 9 | - | pF | |
| Effective output capacitance time related | C _{o(tr)} *7 | $V_{\rm DS} = 0V$ to 400V | - | 41 | - | | |
| Turn - on delay time | t _{d(on)} *5 | $V_{DD} \simeq 400$ V, V_{GS} = 10V | - | 15 | - | | |
| Rise time | t _r *5 | I _D = 3A | - | 30 | - | 20 | |
| Turn - off delay time | $t_{d(off)}$ *5 | R _L ≃ 133Ω | _ | 40 | - | ns | |
| Fall time | t _f *5 | R _G = 10Ω | - | 45 | - | | |

• Gate charge characteristics ($T_a = 25^{\circ}C$)

| Deremeter | Sumbol | Conditions | Values | | | Unit |
|----------------------|---------------------------|--|--------|------|------|------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Onit |
| Total gate charge | Q _g *5 | $V_{DD} \simeq 400 V$ | - | 22 | - | |
| Gate - Source charge | Q _{gs} *5 | I _D = 6A | - | 3 | - | nC |
| Gate - Drain charge | ${\sf Q}_{\sf gd}{}^{*5}$ | V _{GS} = 10V | - | 9 | - | |
| Gate plateau voltage | V _(plateau) | $V_{DD} \simeq 400$ V, I _D = 6A | - | 4.0 | - | V |



•Body diode characteristics (Source-Drain) (T_a = 25°C)

| Parameter | Symbol | Conditions | Values | | | Unit | |
|---|---------------------|---|--------|------|------|------|--|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit | |
| Source current | I_S^{*1} | T 05%0 | - | - | 6 | А | |
| Pulsed source current | I_{SP}^{*2} | T _C = 25°C | - | - | 18 | А | |
| Source-Drain voltage V _{SD} *5 | | V _{GS} = 0V, I _S = 6A | - | - | 1.5 | V | |
| Reverse recovery time | t _{rr} *5 | | - | 400 | - | ns | |
| Reverse recovery charge | Q _{rr} *5 | I _S = 6A di/dt = 100A/µs | - | 5000 | - | μC | |
| Peak reverse recovery current | ۲ <mark>.</mark> *5 | | - | 25 | - | А | |

*1 Limited only by maximum channel temperature allowed.

- *2 Pw \leq 10µs, Duty cycle \leq 1%
- *3 L \doteqdot 100mH, V_{DD}=50V, R_G=25 Ω , STARTING T_i=25°C
- *4 T_C=25°C
- *5 Pulsed
- *6 Co(er) is a fixed capacitance that gives the same stored energy as Coss while V_{DS} is rising from 0 to 50% V_{DSS}.

*6 Co(er) is a fixed capacitance that gives the same charging time as Coss while V_{DS} is rising from 0 to 50% V_{DSS}.



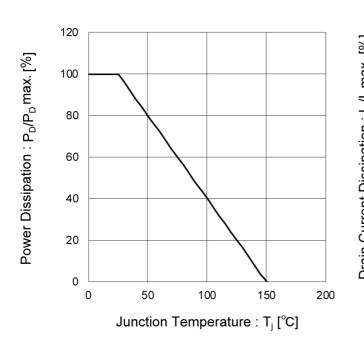


Fig.1 Power Dissipation Derating Curve

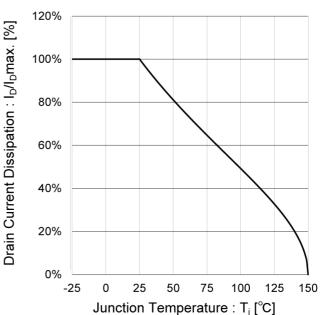


Fig.2 Drain Current Derating Curve

| Fig.3 Normalized Transient Thermal |
|------------------------------------|
| Resistance vs. Pulse Width |

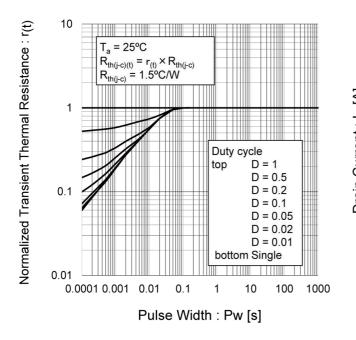
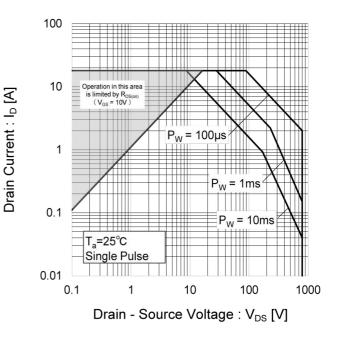


Fig.4 Maximum Safe Operating Area





ROHM

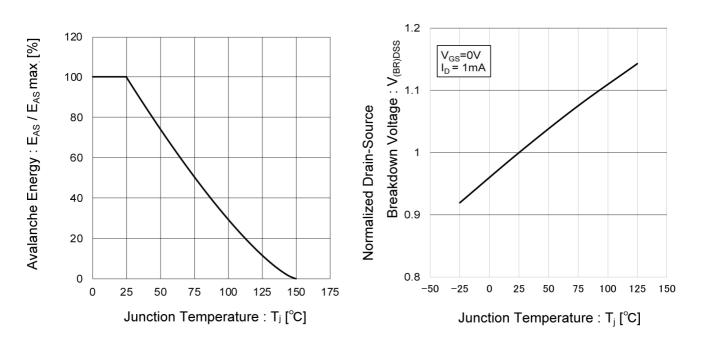


Fig.5 Avalanche Energy Derating Curve

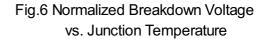
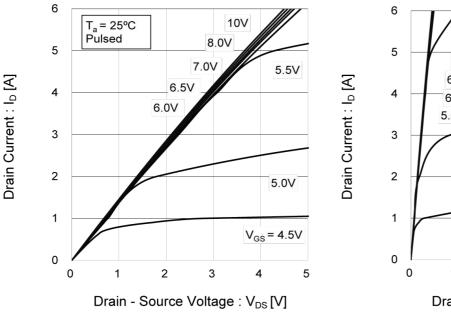
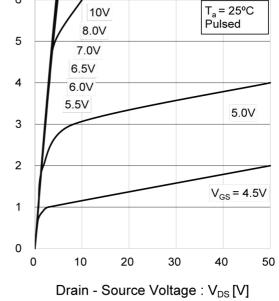


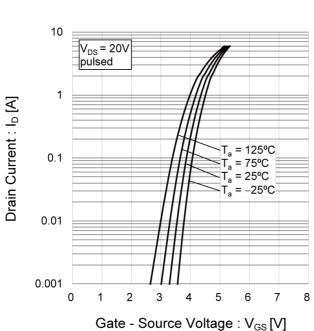
Fig.7 Output Characteristics(I))











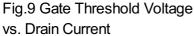


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

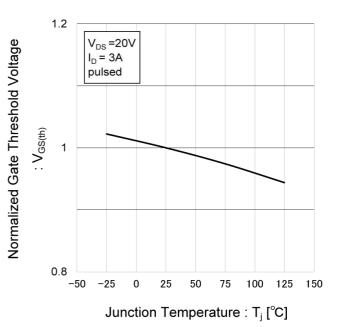
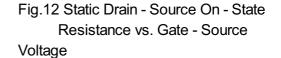
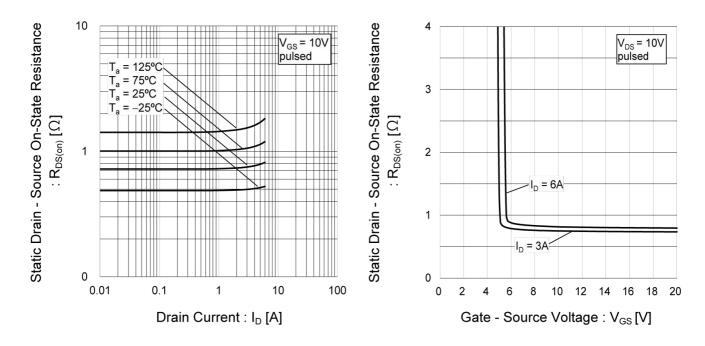


Fig.10 Normalized Gate Threshold Voltage vs. Junction Temperature







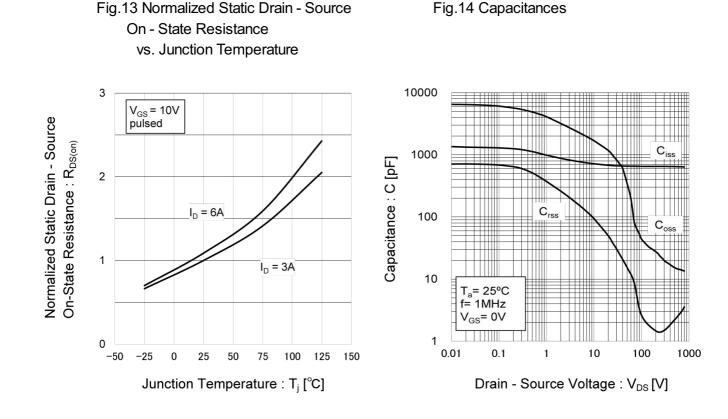
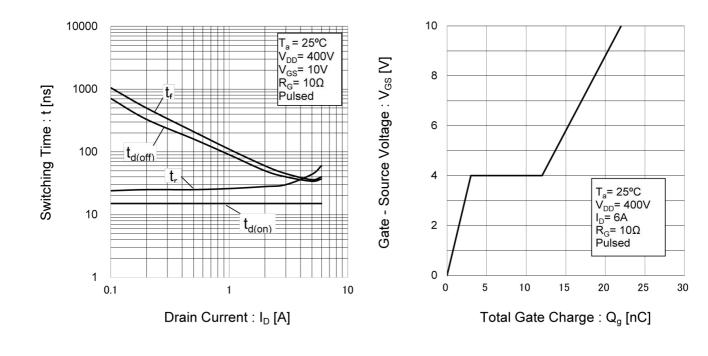


Fig.15 Switching Times

Fig.16 Gate Charge







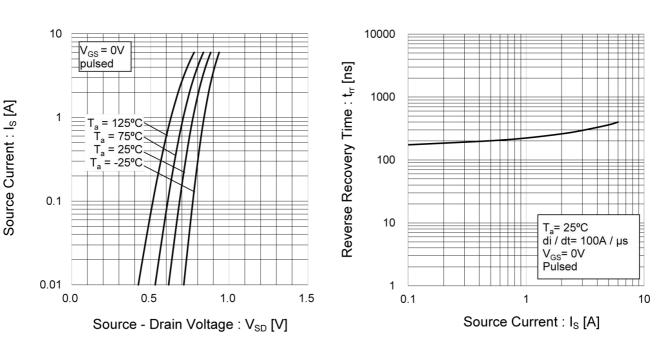


Fig.17 Source Current vs. Source - Drain Voltage Fig.18 Reverse Recovery Time vs. Source Current





Measurement circuits

Fig.1-1 Switching time measurement circuit

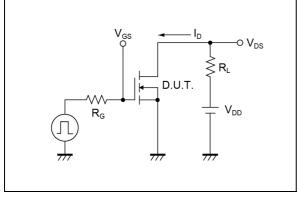


Fig.2-1 Gate charge measurement circuit

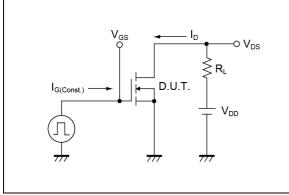


Fig.3-1 Avalanche measurement circuit

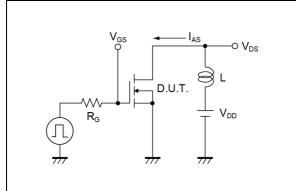


Fig.4-1 trr measurement Circuit

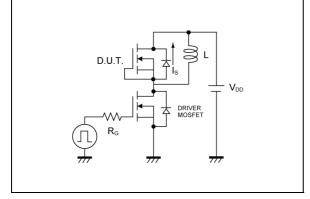


Fig.1-2 Switching waveforms

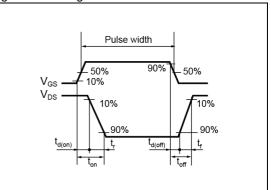


Fig.2-2 Gate charge waveform

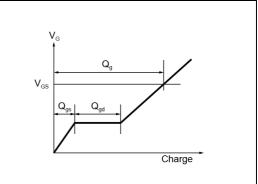


Fig.3-2 Avalanche waveform

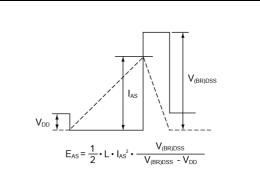
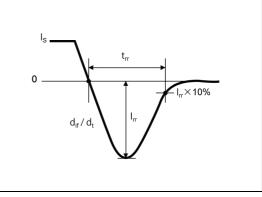
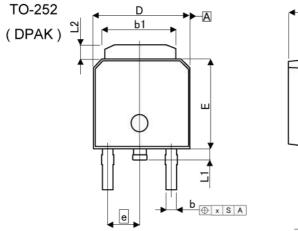


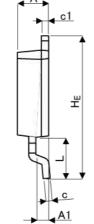
Fig.4-2 trr waveform

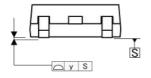


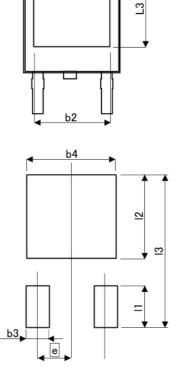


Dimensions









Pattern of terminal position areas [Not a recommended pattern of soldering pads]

| DIM | MILIMETERS | | INC | HES |
|-------|------------|-------|-----------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 2.20 | 2.40 | 0.087 | 0.094 |
| A1 | 0.70 | 1.10 | 0.028 | 0.043 |
| b | 0.60 | 0.90 | 0.024 | 0.035 |
| b1 | 5.20 | 5.50 | 0.205 | 0.217 |
| b2 | 4. | 80 | 0.1 | 89 |
| С | 0.40 | 0.60 | 0.016 | 0.024 |
| c1 | 0.40 | 0.60 | 0.016 | 0.024 |
| D | 6.40 | 6.80 | 0.252 | 0.268 |
| e | 2. | 30 | 0.0 |)91 |
| E | 6.00 | 6.40 | 0.236 | 0.252 |
| HE | 9.40 | 10.40 | 0.370 | 0.409 |
| L | 2. | 90 | 0.1 | 14 |
| L1 | 0.60 | 1.00 | 0.024 | 0.039 |
| L2 | 0.70 | 1.30 | 0.028 | 0.051 |
| L3 | 5. | 30 | 0.2 | 209 |
| x | ¥ () | 0.25 | 5 (1 2) | 0.010 |
| у | 2 | 0.10 | (7) | 0.004 |
| DIM - | MILIME | ETERS | INC | HES |
| | MIN | MAX | MIN | MAX |
| b3 | ÷ | 1.15 | (#4) | 0.045 |
| b4 | - | 5.55 | (7) | 0.219 |
| 11 | ÷ | 2.77 | 1940 - 1 | 0.109 |
| 12 | | 5.50 | (2) | 0.217 |
| 13 | - | 10.40 | 260 | 0.409 |

Dimension in mm/inches





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|--------|----------|------------|---------|
| CLASSⅢ | CLASSⅢ | CLASS II b | CLASSII |
| CLASSⅣ | CLASSIII | CLASSII | CLASSI |

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 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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